



# SOT612-4

plastic thermal enhanced low profile quad flat package; 144 leads; body 20 x 20 x 1.4 mm; exposed die pad

8 February 2016

Package information

## 1. Package summary

<b>Terminal position code</b>	Q (quad)
<b>Package type descriptive code</b>	HLQFP144
<b>Package type industry code</b>	HLQFP144
<b>Package style descriptive code</b>	HLQFP (thermal enhanced low profile quad flat package)
<b>Package style suffix code</b>	NA (not applicable)
<b>Package body material type</b>	P (plastic)
<b>JEDEC package outline code</b>	MS-026
<b>Mounting method type</b>	S (surface mount)
<b>Issue date</b>	18-1-2008

Table 1. Package summary

Symbol	Parameter	Min	Typ	Nom	Max	Unit
D	package length	19.9	-	20	20.1	mm
E	package width	19.9	-	20	20.1	mm
A	seated height	1.4	-	1.5	1.6	mm
A <sub>2</sub>	package height	1.35	-	1.4	1.45	mm
e	nominal pitch	-	-	0.5	-	mm
n <sub>2</sub>	actual quantity of termination	-	-	144	-	

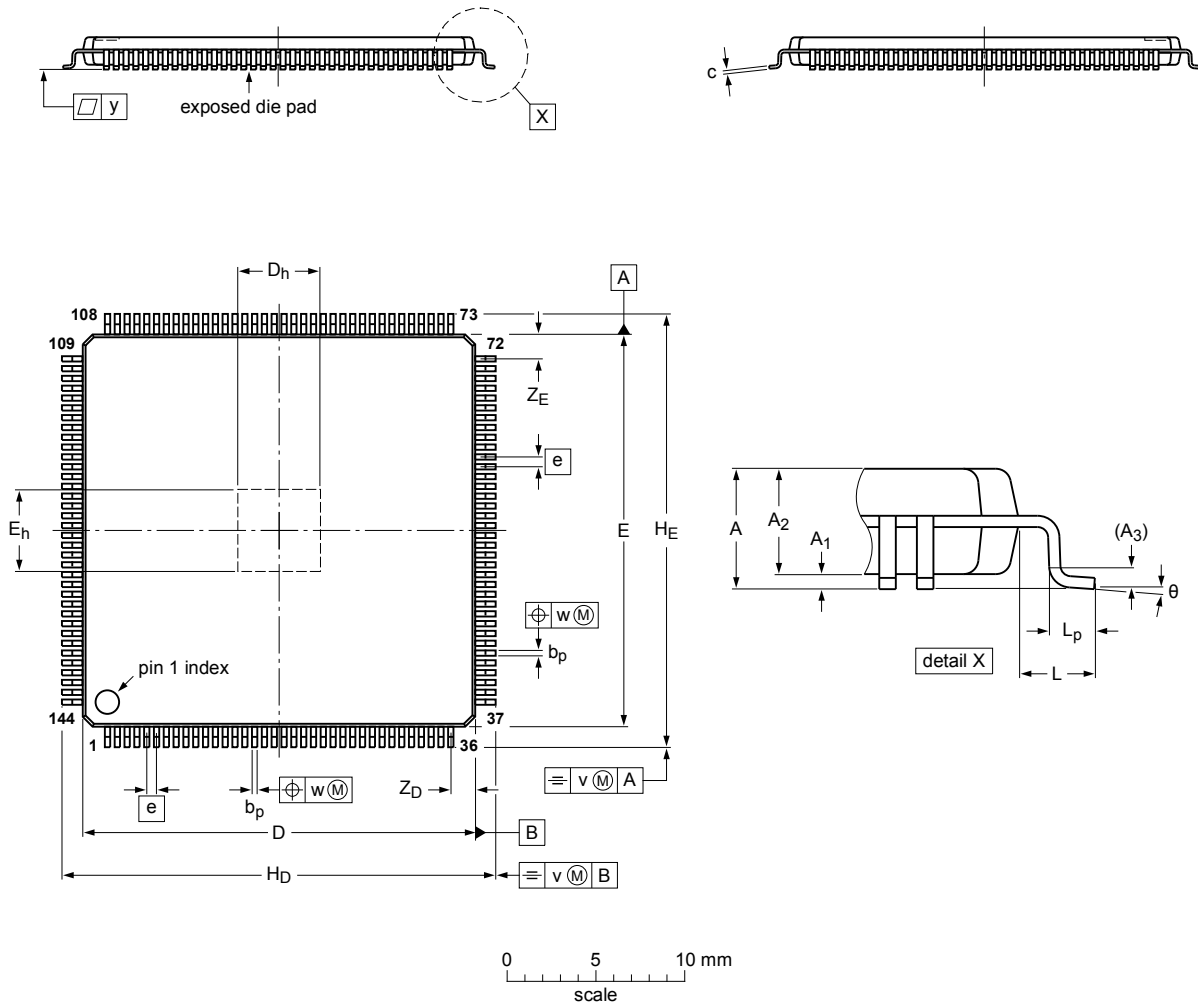


plastic thermal enhanced low profile quad flat package; 144 leads; body 20 x 20 x 1.4 mm; exposed die pad

## 2. Package outline

HLQFP144: plastic thermal enhanced low profile quad flat package; 144 leads; body 20 x 20 x 1.4 mm; exposed die pad

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**DIMENSIONS** (mm are the original dimensions)

UNIT	A <sub>max</sub>	A <sub>1</sub>	A <sub>2</sub>	A <sub>3</sub>	b <sub>p</sub>	c	D <sup>(1)</sup>	D <sub>h</sub>	E <sup>(1)</sup>	E <sub>h</sub>	e	H <sub>D</sub>	H <sub>E</sub>	L	L <sub>p</sub>	v	w	y	Z <sub>D</sub> <sup>(1)</sup>	Z <sub>E</sub> <sup>(1)</sup>	θ
mm	1.6	0.12 0.05	1.45 1.35	0.25	0.27 0.17	0.20 0.09	20.1 19.9	4.3 4.1	20.1 19.9	4.3 4.1	0.5	22.15 21.85	22.15 21.85	1	0.75 0.45	0.2	0.08	0.08	1.4 1.1	1.4 1.1	7° 0°

**Note**

1. Plastic or metal protrusions of 0.25 mm maximum per side are not included.

OUTLINE VERSION	REFERENCES				EUROPEAN PROJECTION	ISSUE DATE
	IEC	JEDEC	JEITA			
SOT612-4		MS-026				07-12-11 08-01-18

Fig. 1. Package outline HLQFP144 (SOT612-4)

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### 3. Soldering

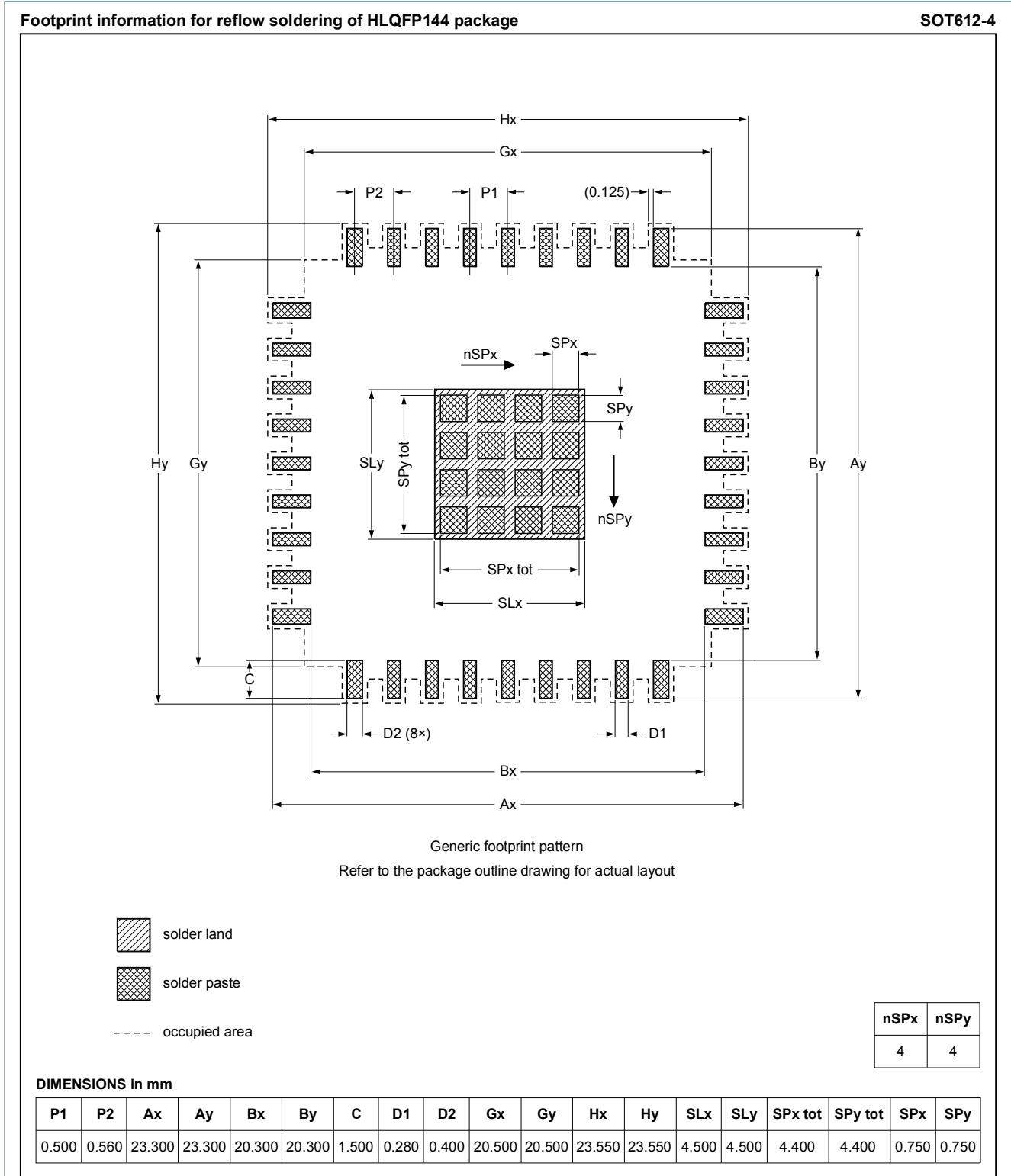


Fig. 2. Reflow soldering footprint for HLQFP144 (SOT612-4)

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## 4. Legal information

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